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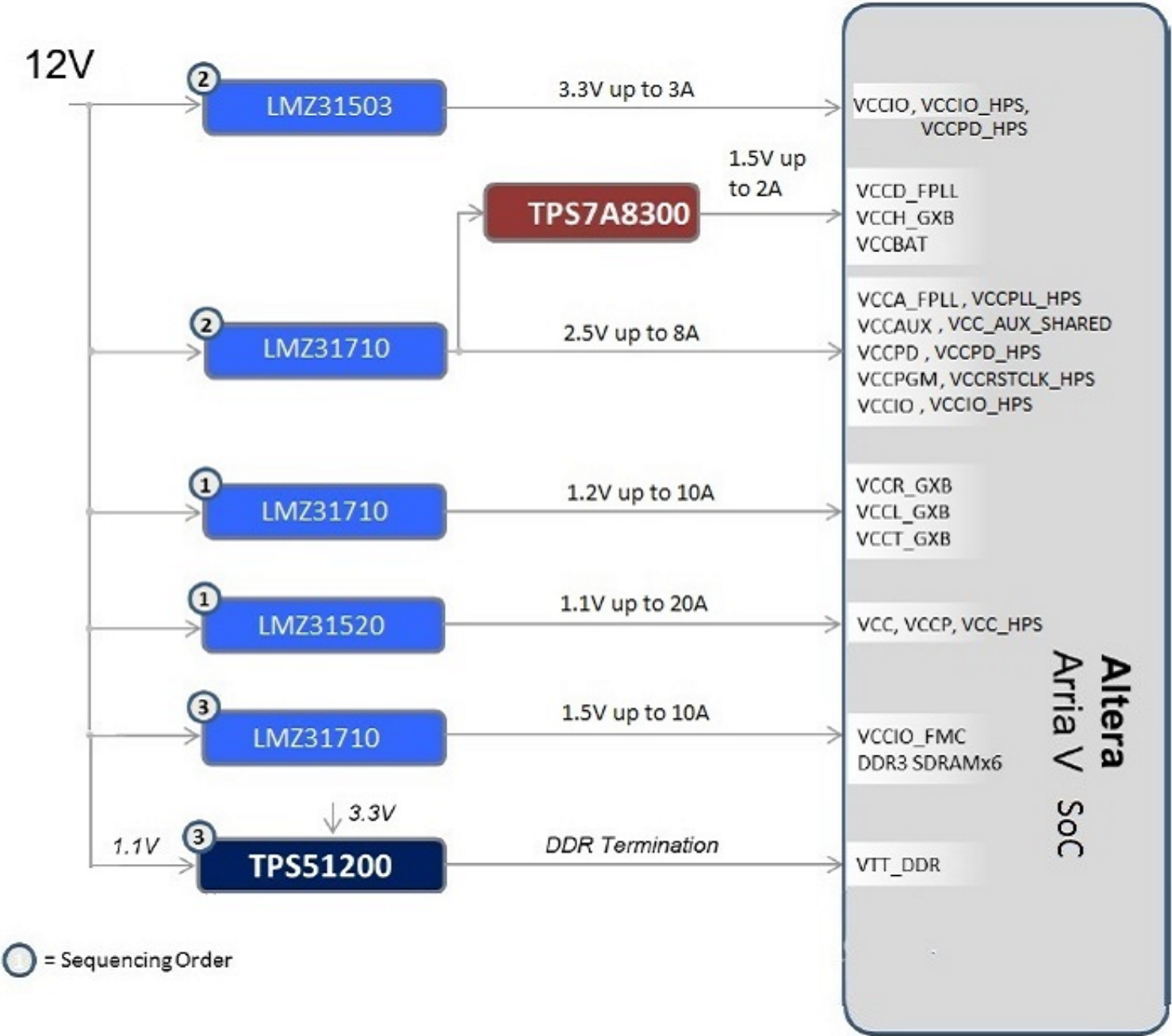
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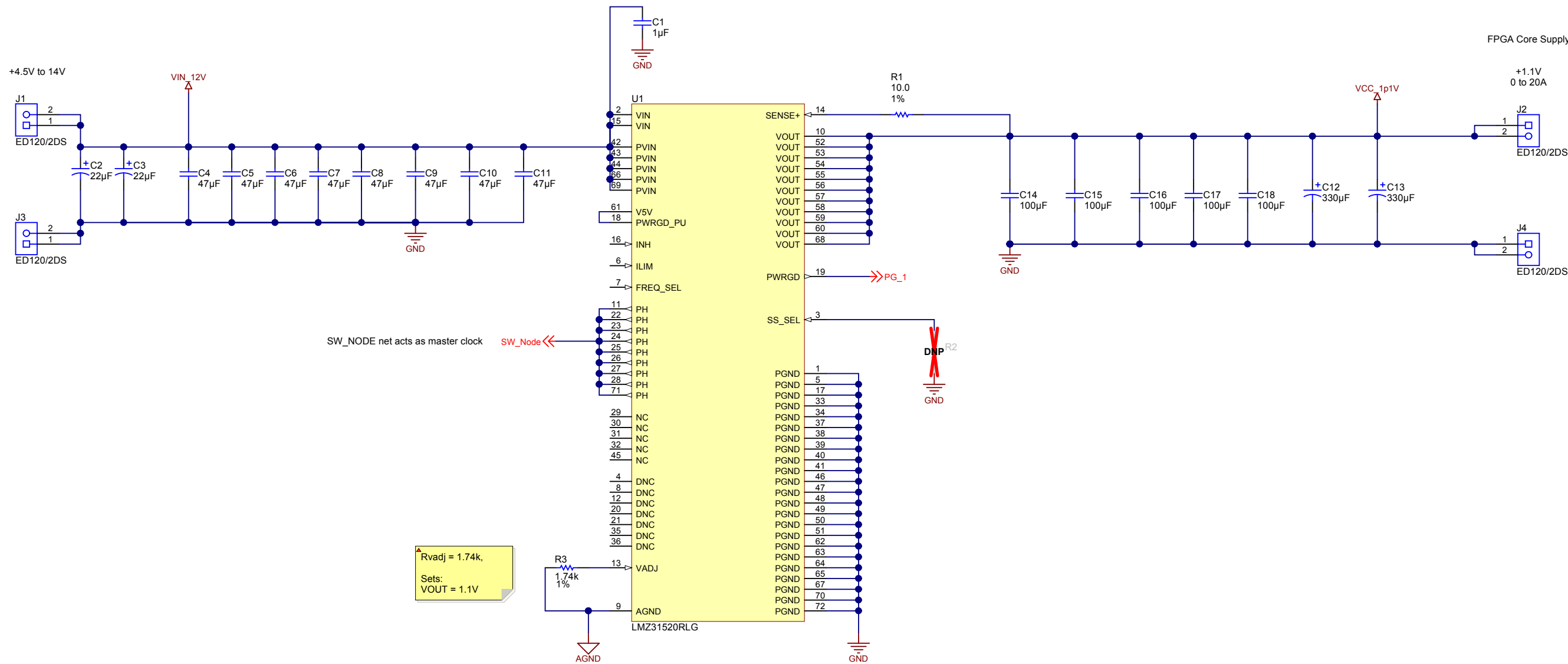
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Revision History	
Revision	Notes



FPGA Core Power Supply



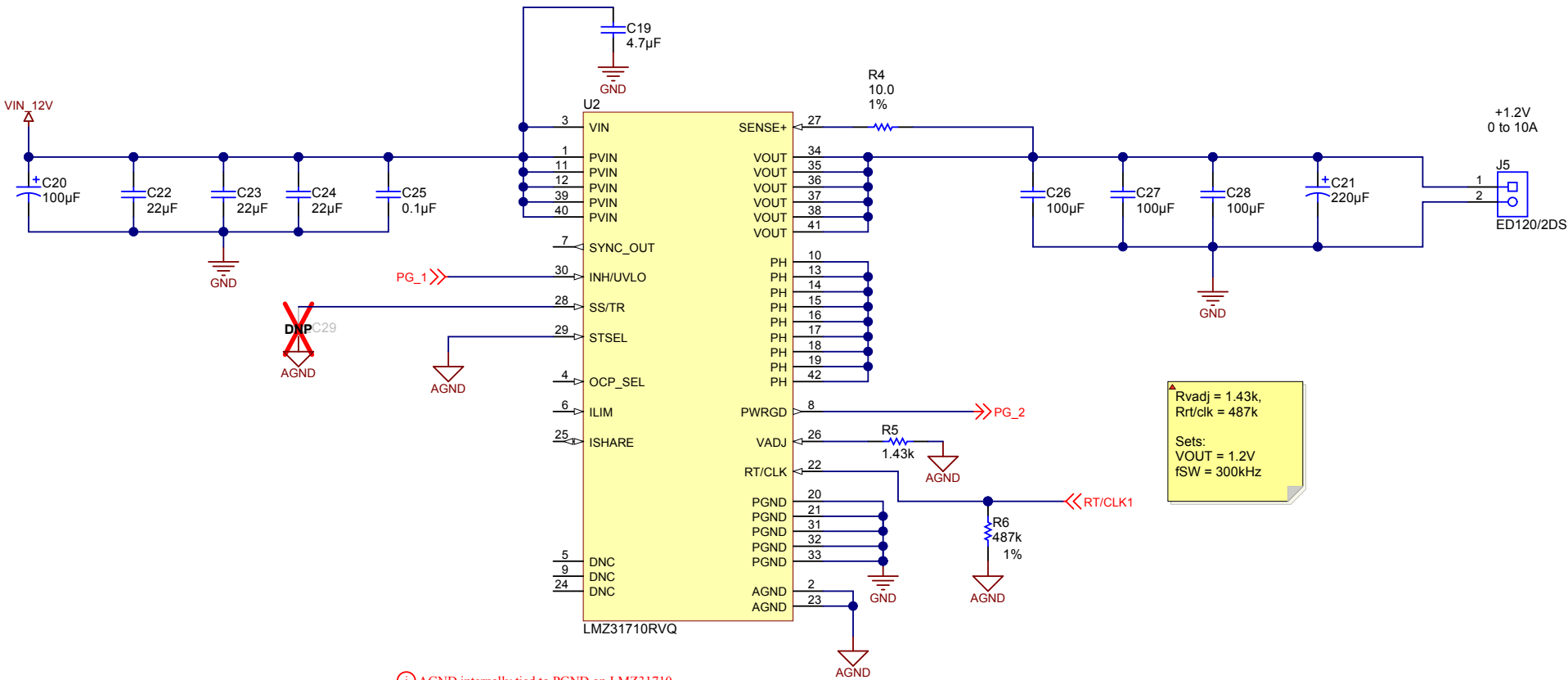
- AGND internally tied to PGND on LMZ31520
- PH pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or net to this pin.

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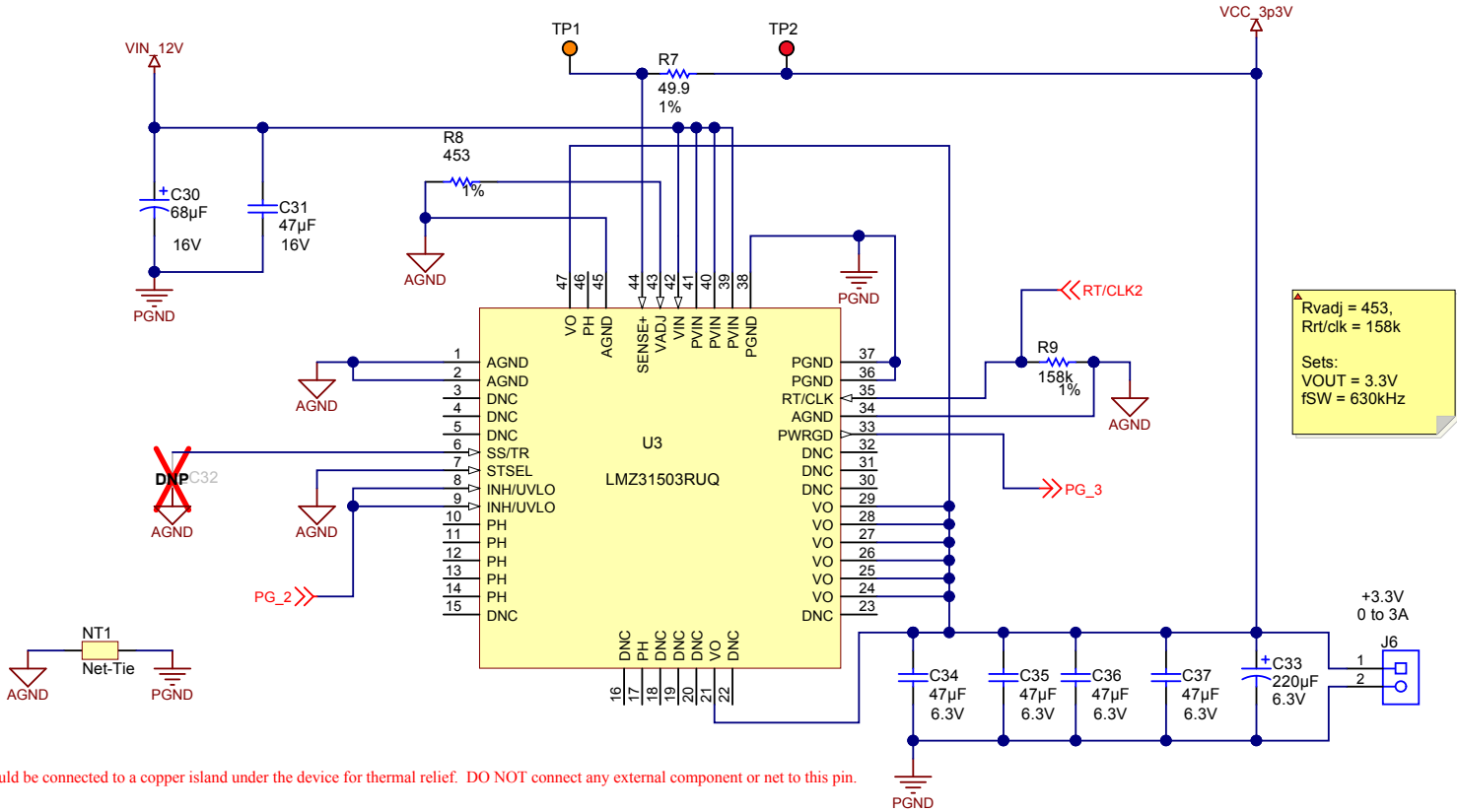
Number: SAT0090	Rev: E1	Designed for: Public Release	Mod. Date: 4/22/2014
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: Altera Arria V SoC Power Supply	
Drawn By: Sami Sirhan	File: Page1.SchDoc	Sheet Title:	
Engineer: Sami Sirhan	Contact: http://www.ti.com/support	Sheet: 2 of 5	Size: B
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FPGA Power Supplies




- AGND internally tied to PGND on LMZ31710
- PH pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or net to this pin.

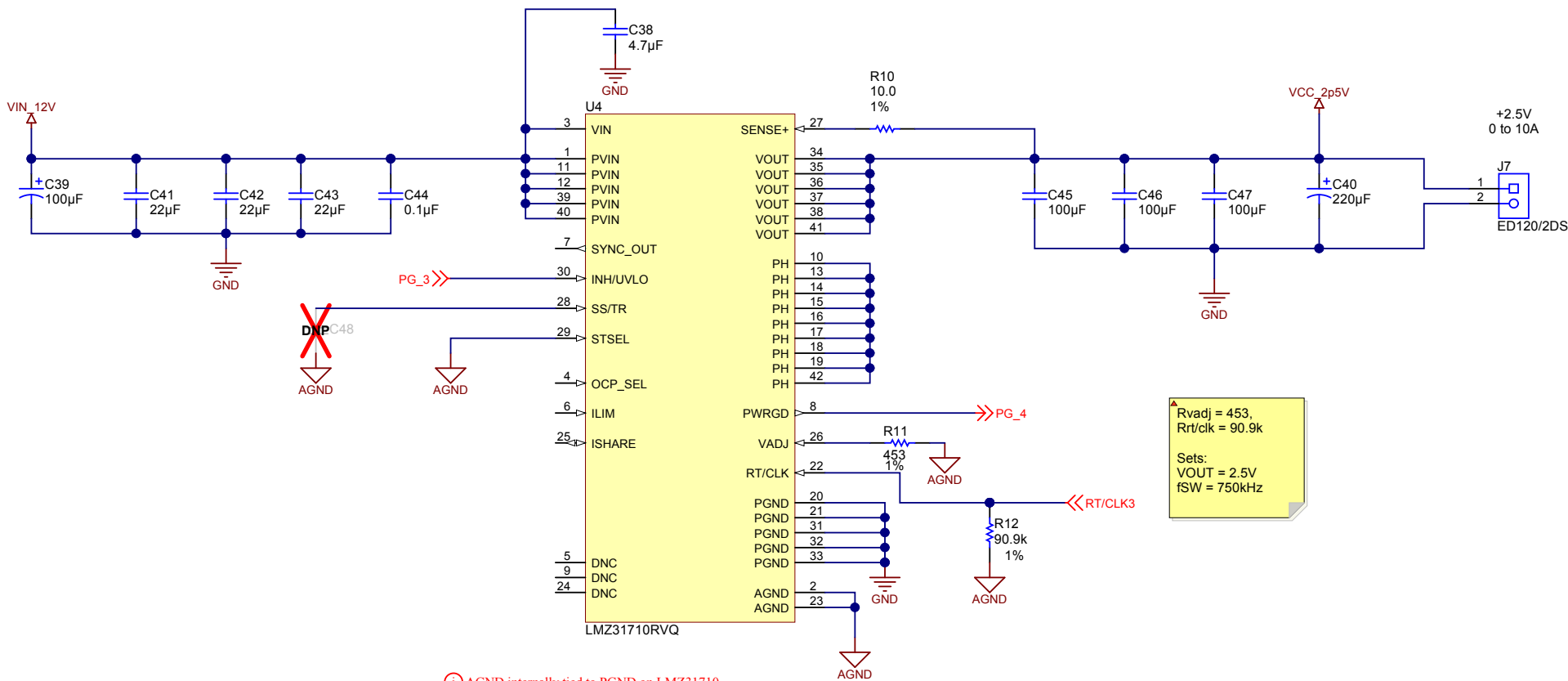


- PH pins should be connected to a copper island under the device for thermal relief. DO NOT connect any external component or net to this pin.

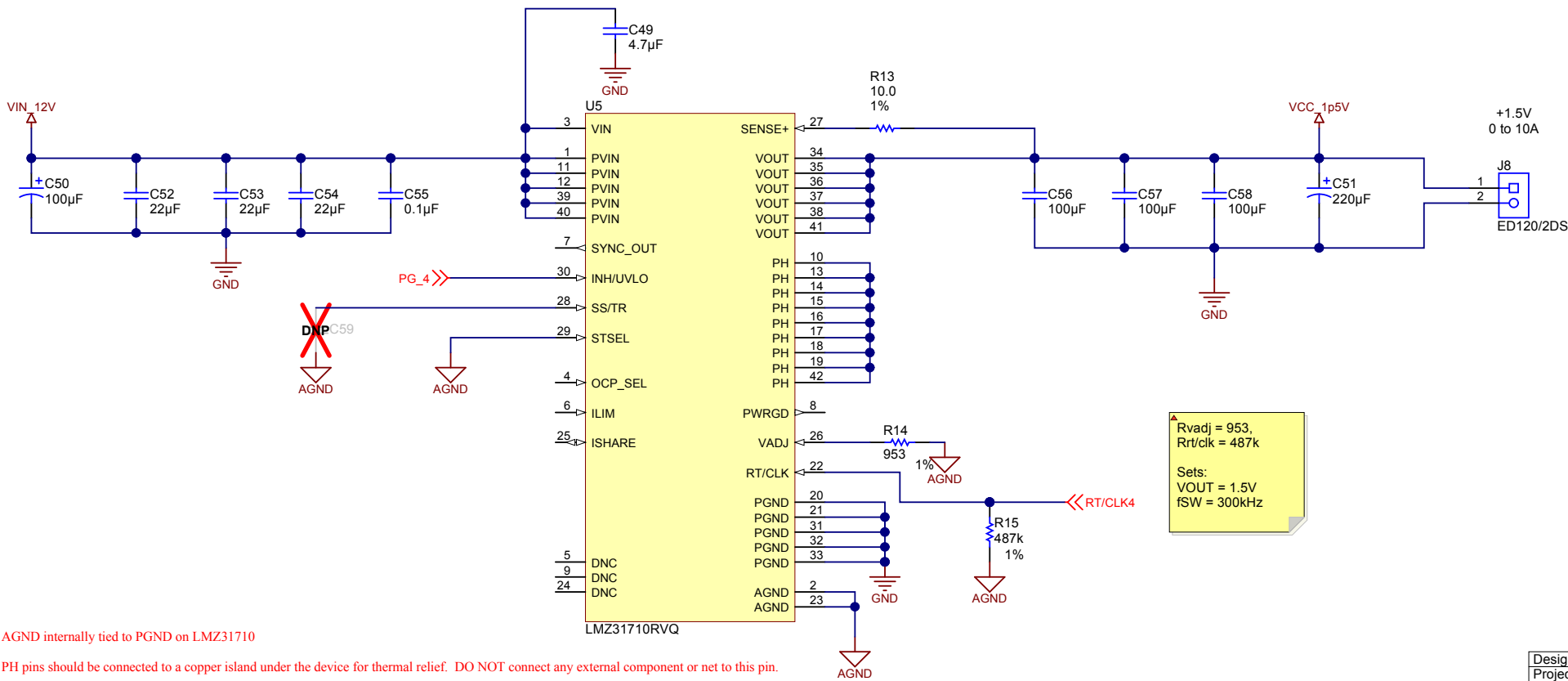
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Designed for: Public Release	Mod. Date: 4/22/2014	
Project Title: Altera Arria V SoC Power Supply	Rev: E1	
Sheet Title:	Assembly Variant: 001	
SVN Rev: Not in version control	File: Page2.SchDoc	
Drawn By:	Size: B	
Engineer: Sami Sirhan	Contact: http://www.ti.com/support	© Texas Instruments 2014

FPGA Power Supplies



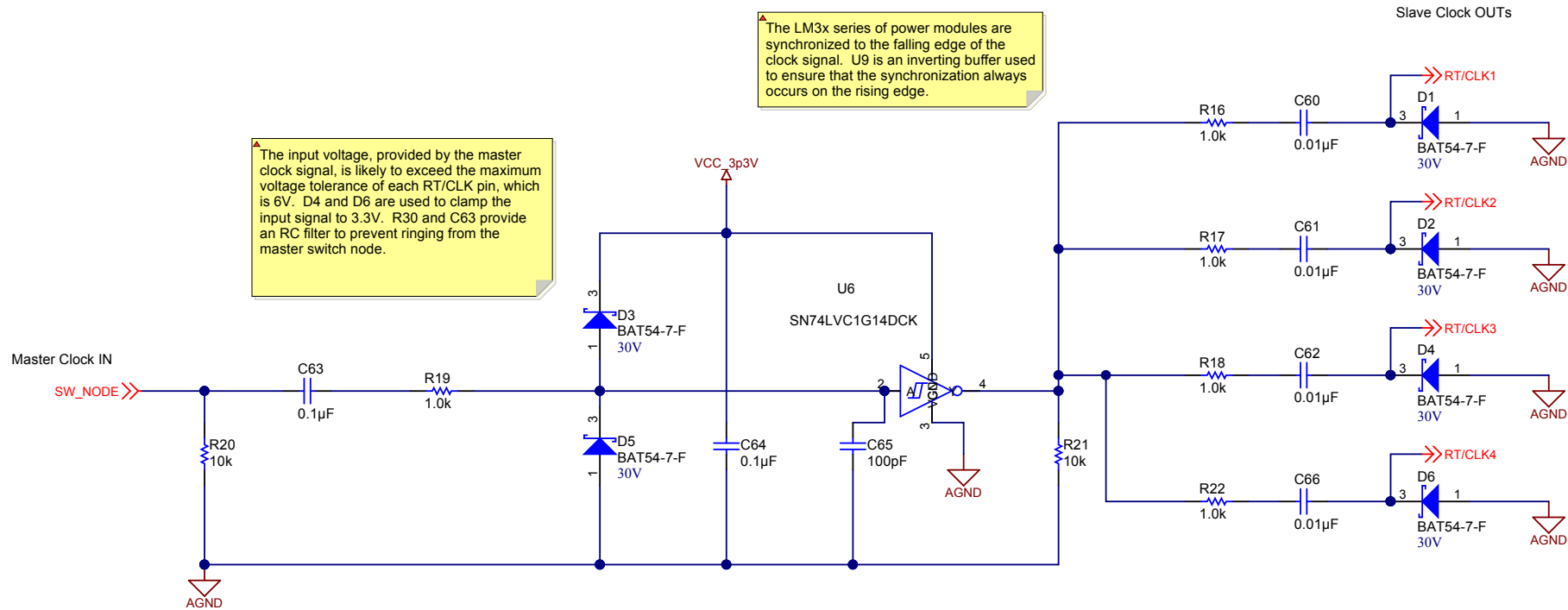
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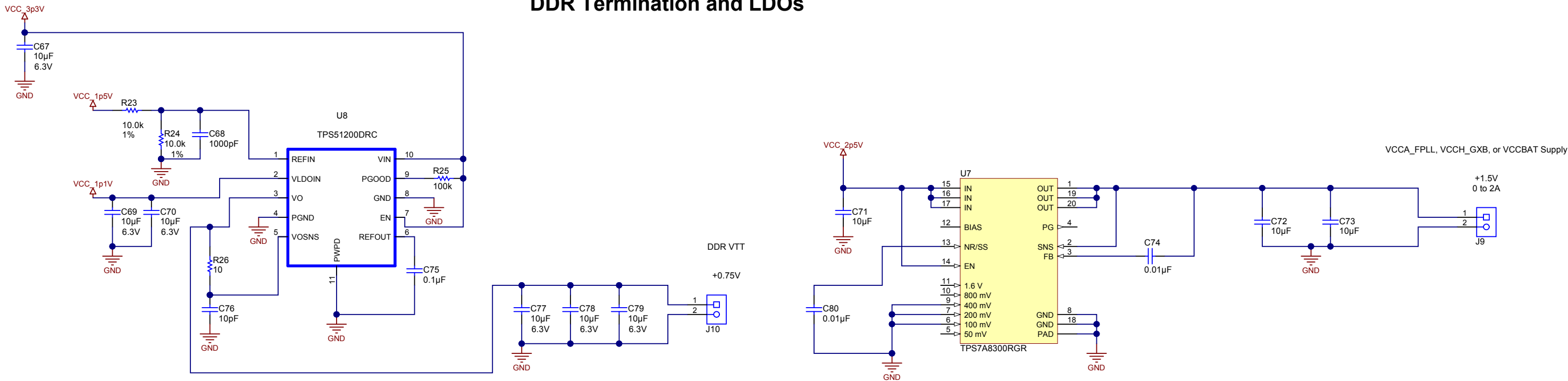
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Clock Synchronization Circuit



DDR Termination and LDOs



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